

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	3.0	A
T_{OP}	Operating Temperature	-40 to 125	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

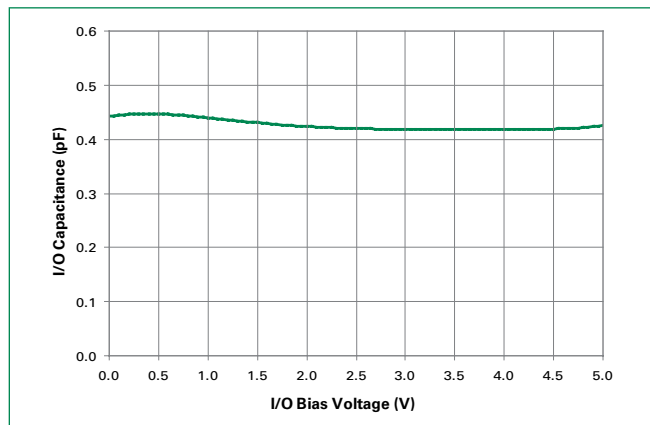
CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Electrical Characteristics ($T_{OP}=25^{\circ}C$)

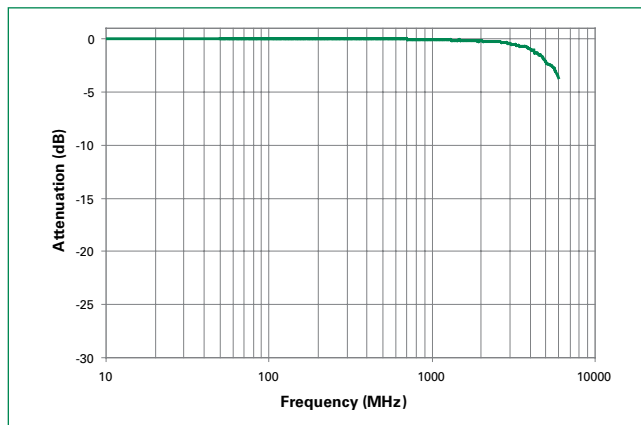
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	$I_R \leq 1\mu A$			6.0	V
Reverse Leakage Current	I_{LEAK}	$V_R=5V$, Any I/O to GND		0.1	0.5	μA
Clamp Voltage ¹	V_C	$I_{PP}=1A$, $t_p=8/20\mu s$, Fwd		10.8		V
		$I_{PP}=2A$, $t_p=8/20\mu s$, Fwd		12.3		V
Dynamic Resistance	R_{DYN}	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.5		Ω
ESD Withstand Voltage ¹	V_{ESD}	IEC61000-4-2 (Contact)	± 8			kV
		IEC61000-4-2 (Air)	± 15			kV
Diode Capacitance ¹	$C_{I/O-GND}$	Reverse Bias=0V		0.45		pF

Note: ¹ Parameter is guaranteed by design and/or device characterization.

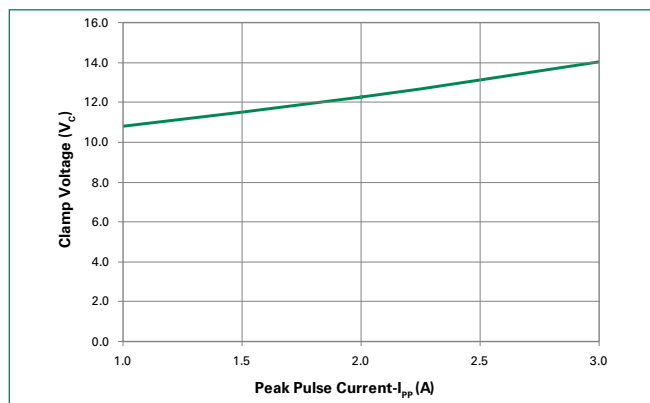
Capacitance vs. Bias Voltage



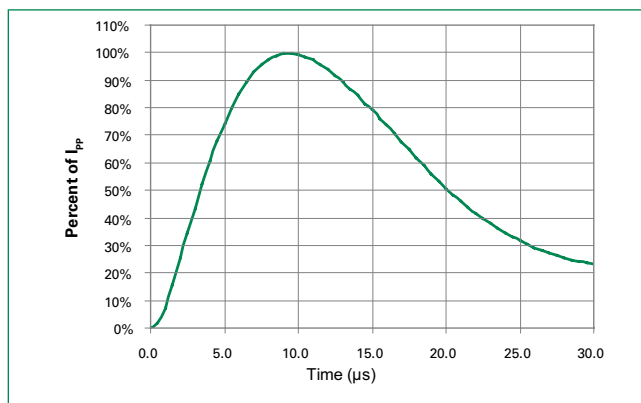
Insertion Loss (S21) I/O to GND



Clamping Voltage vs. I_{PP}

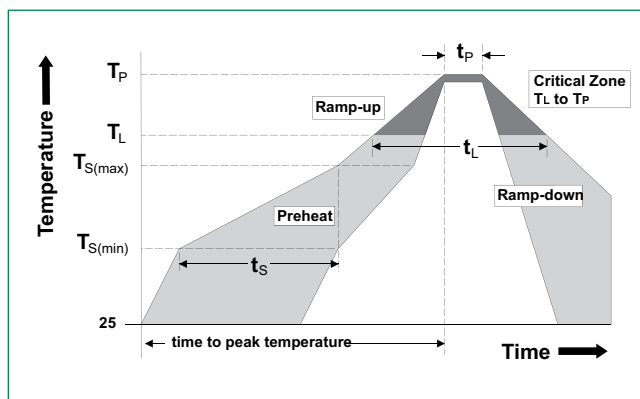


Pulse Waveform

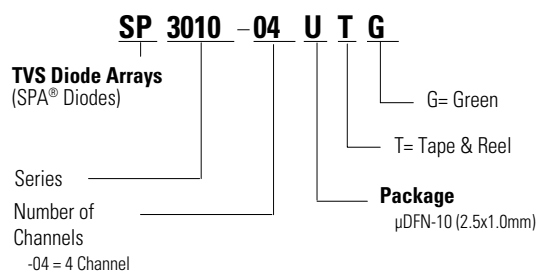


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



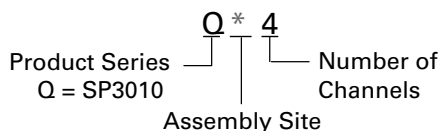
Part Numbering System



Product Characteristics

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substitute Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

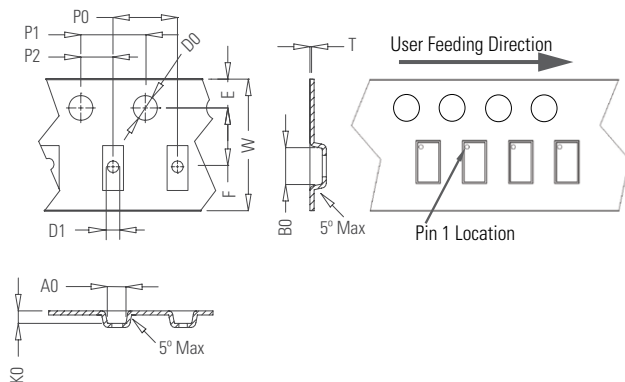
Part Marking System



Ordering Information

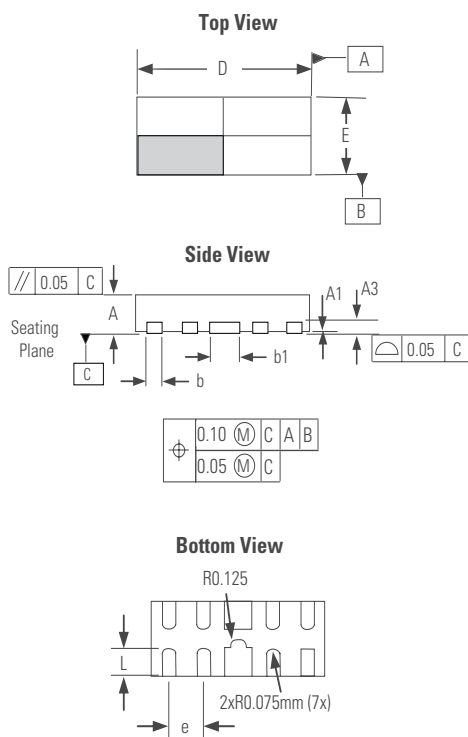
Part Number	Package	Min. Order Qty.
SP3010-04UTG	μ DFN-10	3000

Embossed Carrier Tape & Reel Specification — μ DFN-10



Package	μ DFN-10 (2.5x1.0x0.5mm)
Symbol	Millimeters
A0	1.30 ± 0.10
B0	2.83 ± 0.10
D0	Ø 1.50 + 0.10
D1	Ø 1.00 + 0.25
E	1.75 ± 0.10
F	3.50 ± 0.05
K0	0.65 ± 0.10
P0	4.00 ± 0.10
P1	4.00 ± 0.10
P2	2.00 ± 0.05
T	0.254 ± 0.02
W	8.00 + 0.30 /- 0.10

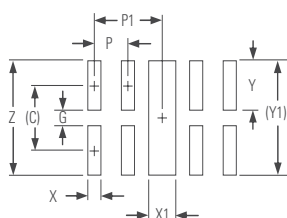
Package Dimensions — μ DFN-10 (2.5x1.0x0.5mm)



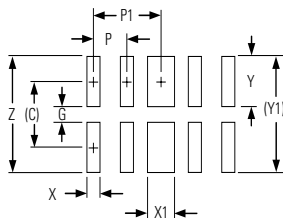
Package	μ DFN-10 (2.5x1.0x0.5mm)					
JEDEC	MO-229					
Symbol	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.48	0.515	0.55	0.019	0.020	0.021
A1	0.00	—	0.05	0.000		0.022
A3	0.125 Ref			0.005 Ref		
b	0.15	0.20	0.25	0.006	0.008	0.012
b1	0.35	0.40	0.45	0.014	0.016	0.018
D	2.40	2.50	2.60	0.094	0.098	0.102
E	0.90	1.00	1.10	0.035	0.039	0.043
e	0.50 BSC			0.020 BSC		
L	0.30	0.365	0.43	0.012	0.014	0.016

Soldering Pad Layout Dimensions		
Symbol	Inch	Millimeter
C	(0.034)	(0.875)
G	0.008	0.20
P	0.020	0.50
P1	0.039	1.00
X	0.008	0.20
X1	0.016	0.40
Y	0.027	0.675
Y1	(0.061)	(1.55)
Z	0.061	1.55

Recommended Soldering Pad Layout



Alternative Soldering Pad Layout



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